

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**Industrial communication networks – Fieldbus specifications –  
Part 4-3: Data-link layer protocol specification – Type 3 elements**

**Réseaux de communication industriels – Spécifications des bus de terrain –  
Partie 4-3: Spécification du protocole de la couche liaison de données –  
Éléments de type 3**



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## CONTENTS

FOREWORD.....	6
INTRODUCTION.....	8
1 Scope.....	9
1.1 General.....	9
1.2 Specifications.....	9
1.3 Procedures.....	9
1.4 Applicability.....	9
1.5 Conformance.....	10
2 Normative references.....	10
3 Terms, definitions, symbols and abbreviations.....	10
3.1 Reference model terms and definitions.....	10
3.2 Service convention terms and definitions.....	12
3.3 Common terms and definitions.....	13
3.4 Additional Type 3 definitions.....	15
3.5 Common symbols and abbreviations.....	17
3.6 Type 3 symbols and abbreviations.....	18
4 Common DL-protocol elements.....	22
4.1 Frame check sequence.....	22
5 Overview of the DL-protocol.....	25
5.1 General.....	25
5.2 Overview of the medium access control and transmission protocol.....	25
5.3 Transmission modes and DL-entity.....	26
5.4 Service assumed from the PhL.....	31
5.5 Operational elements.....	35
5.6 Cycle and system reaction times.....	50
6 General structure and encoding of DLPDUs, and related elements of procedure.....	53
6.1 DLPDU granularity.....	53
6.2 Length octet (LE, LEr).....	54
6.3 Address octet.....	54
6.4 Control octet (FC).....	57
6.5 DLPDU content error detection.....	61
6.6 DATA_UNIT.....	61
6.7 Error control procedures.....	62
7 DLPDU-specific structure, encoding and elements of procedure.....	63
7.1 DLPDUs of fixed length with no data field.....	63
7.2 DLPDUs of fixed length with data field.....	65
7.3 DLPDUs with variable data field length.....	67
7.4 Token DLPDU.....	68
7.5 ASP DLPDU.....	69
7.6 SYNCH DLPDU.....	69
7.7 Time Event (TE) DLPDU.....	69
7.8 Clock Value (CV) DLPDU.....	70
7.9 Transmission procedures.....	70
8 Other DLE elements of procedure.....	73
8.1 DL-entity initialization.....	73
8.2 States of the media access control of the DL-entity.....	74

8.3	Clock synchronization protocol .....	80
Annex A	(normative) DL-Protocol state machines .....	85
A.1	Overall structure .....	85
A.2	Variation of state machines in different devices .....	86
A.3	DL Data Resource .....	87
A.4	FLC / DLM .....	91
A.4.1	Primitive definitions .....	91
A.4.2	State machine description .....	96
A.5	MAC .....	115
A.5.1	Primitive definitions .....	115
A.5.2	State machine description .....	115
A.6	SRU .....	141
A.6.1	Overview .....	141
A.6.2	Character send SM(CTX) .....	142
A.6.3	Character receive SM (CRX) .....	143
A.6.4	Timer-SM (TIM) .....	143
A.6.5	Primitive definition of SRC .....	144
A.6.6	State machine description .....	145
Annex B	(informative) Type 3 (synchronous): exemplary FCS implementations .....	160
Annex C	(informative) Type 3: Exemplary token procedure and message transfer periods .....	162
C.1	Procedure of token passing .....	162
C.2	Examples for token passing procedure .....	163
C.3	Examples for message transfer periods – asynchronous transmission .....	168
	Bibliography .....	170
Figure 1	– Relationships of DLSAPs, DLSAP-addresses and group DL-addresses .....	14
Figure 2	– Logical token-passing ring .....	28
Figure 3	– PhL data service for asynchronous transmission .....	32
Figure 4	– Idle time $T_{ID1}$ .....	37
Figure 5	– Idle time $T_{ID2}$ (SDN, CS) .....	38
Figure 6	– Idle time $T_{ID2}$ (MSRD) .....	38
Figure 7	– Slot time $T_{SL1}$ .....	39
Figure 8	– Slot time $T_{SL2}$ .....	39
Figure 9	– Slot time $T_{SL1}$ .....	44
Figure 10	– Slot time $T_{SL2}$ .....	44
Figure 11	– Token transfer period .....	50
Figure 12	– Message transfer period .....	51
Figure 13	– UART character .....	53
Figure 14	– Octet structure .....	54
Figure 15	– Length octet coding .....	54
Figure 16	– Address octet coding .....	55
Figure 17	– DAE/SAE octet in the DLPDU .....	56
Figure 18	– Address extension octet .....	56
Figure 19	– FC octet coding for send/request DLPDUs .....	58
Figure 20	– FC octet coding for acknowledgement or response DLPDUs .....	58

Figure 21 – FCS octet coding.....	61
Figure 22 – Data field .....	62
Figure 23 – Ident user data.....	62
Figure 24 – DLPDUs of fixed length with no data field.....	64
Figure 25 – DLPDUs of fixed length with no data field.....	65
Figure 26 – DLPDUs of fixed length with data field .....	66
Figure 27 – DLPDUs of fixed length with data field .....	66
Figure 28 – DLPDUs with variable data field length.....	67
Figure 29 – DLPDUs with variable data field length.....	68
Figure 30 – Token DLPDU .....	68
Figure 31 – Token DLPDU .....	69
Figure 32 – Send/request DLPDU of fixed length with no data .....	70
Figure 33 – Token DLPDU and send/request DLPDU of fixed length with data.....	71
Figure 34 – Send/request DLPDU with variable data field length.....	71
Figure 35 – Send/request DLPDU of fixed length with no data .....	72
Figure 36 – Token DLPDU and send/request DLPDU of fixed length with data.....	72
Figure 37 – Send/request DLPDU with variable data field length.....	73
Figure 38 – DL-state-diagram .....	75
Figure 39 – Overview of clock synchronization.....	81
Figure 40 – Time master state machine.....	82
Figure 41 – Time receiver state machine.....	83
Figure 42 – Clock synchronization .....	84
Figure A.1 – Structuring of the protocol machines.....	86
Figure A.2 – Structure of the SRU Machine.....	142
Figure B.1 – Example of FCS generation for Type 3 (synchronous) .....	160
Figure B.2 – Example of FCS syndrome checking on reception for Type 3 (synchronous).....	160
Figure C.1 – Derivation of the token holding time ( $T_{TH}$ ).....	163
Figure C.2 – No usage of token holding time ( $T_{TH}$ ).....	164
Figure C.3 – Usage of token holding time ( $T_{TH}$ ) for message transfer (equivalence between $T_{TH}$ of each Master station).....	165
Figure C.4 – Usage of token holding time ( $T_{TH}$ ) in different working load situations .....	167
Table 1 – FCS length, polynomials and constants by Type 3 synchronous .....	23
Table 2 – Characteristic features of the fieldbus data-link protocol.....	25
Table 3 – Transmission function code.....	59
Table 4 – FCB, FCV in responder .....	60
Table 5 – Operating parameters .....	73
Table A.1 – Assignment of state machines.....	87
Table A.2 – Data resource .....	88
Table A.3 – Primitives issued by DL-User to FLC.....	91
Table A.4 – Primitives issued by FLC to DL-User.....	92
Table A.5 – Primitives issued by DL-User to DLM .....	94
Table A.6 – Primitives issued by DLM to DL-User .....	94

Table A.7 – Parameters used with primitives exchanged between DL-User and FLC.....	95
Table A.8 – Parameters used with primitives exchanged between DL-User and DLM.....	95
Table A.9 – FLC/DLM state table .....	96
Table A.10 – FLC / DLM function table.....	108
Table A.11 – Primitives issued by DLM to MAC.....	115
Table A.12 – Primitives issued by MAC to DLM.....	115
Table A.13 – Parameters used with primitives exchanged between DLM and MAC .....	115
Table A.14 – Local MAC variables .....	116
Table A.15 – MAC state table .....	117
Table A.16 – MAC function table.....	137
Table A.17 – Primitives issued by DLM to SRC .....	144
Table A.18 – Primitives issued by SRC to DLM.....	144
Table A.19 – Primitives issued by MAC to SRC.....	144
Table A.20 – Primitives issued by SRC to MAC.....	145
Table A.21 – Parameters used with primitives exchanged between MAC and SRC .....	145
Table A.22 – FC structure.....	145
Table A.23 – Local variables of SRC.....	146
Table A.24 – SRC state table.....	147
Table A.25 – SRC functions .....	159

Withhold

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**INDUSTRIAL COMMUNICATION NETWORKS –  
FIELDBUS SPECIFICATIONS –****Part 4-3: Data-link layer protocol specification –  
Type 3 elements**

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International Standard IEC 61158-4-3 has been prepared by subcommittee 65C: Industrial networks, of IEC technical committee 65: Industrial-process measurement, control and automation.

This third edition cancels and replaces the second edition published in 2010. This edition constitutes a technical revision.

The changes with respect to the previous edition are listed below:

- Corrections in Table A.15 and Table A.16;
- Expired patent removed and added new patents.

The text of this standard is based on the following documents:

FDIS	Report on voting
65C/762/FDIS	65C/772/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61158 series, published under the general title *Industrial communication networks – Fieldbus specifications*, can be found on the IEC web site

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- withdrawn,
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Withhold

## INTRODUCTION

This part of IEC 61158 is one of a series produced to facilitate the interconnection of automation system components. It is related to other standards in the set as defined by the “three-layer” fieldbus reference model described in IEC 61158-1.

The data-link protocol provides the data-link service by making use of the services available from the physical layer. The primary aim of this standard is to provide a set of rules for communication expressed in terms of the procedures to be carried out by peer data-link entities (DLEs) at the time of communication. These rules for communication are intended to provide a sound basis for development in order to serve a variety of purposes:

- a) as a guide for implementors and designers;
- b) for use in the testing and procurement of equipment;
- c) as part of an agreement for the admittance of systems into the open systems environment;
- d) as a refinement to the understanding of time-critical communications within OSI.

This standard is concerned, in particular, with the communication and interworking of sensors, effectors and other automation devices. By using this standard together with other standards positioned within the OSI or fieldbus reference models, otherwise incompatible systems may work together in any combination.

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Publication	Title
EP 1253494	Control device with fieldbus

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